Bumped Die Outline Drawing



Package Code: DICE DICEW 1.503 x 2.555 x 0.375 mm Body, 0.150mm Pitch PSC-4929-01, Revision: 00, Date Created: Feb 11, 2022

(0.375)0.150 1.503±0.030 72x Ø0.096±0.010 • -(1.130)2.555±0.030 <u>-</u> ፍ -0.150ō -(1.278)— -(1.177)-(1.130)(0.150) (0.050) **TOP VIEW** (0.050)--0.150 (0.120) (0.450) (0.450) (0.662) -(0.752)*-*-(0.752)-**BOTTOM VIEW** _ 0.075±0.008 0.375±0.050 72x 0.020 C SEATING PLANE DETAIL A c SIDE VIEW -(Ø0.080) UBM (0.005)POLYIMIDE SOLDER BUMP [SnAg; 1.8% Ag] (0.075)**DETAIL A** NOTES:

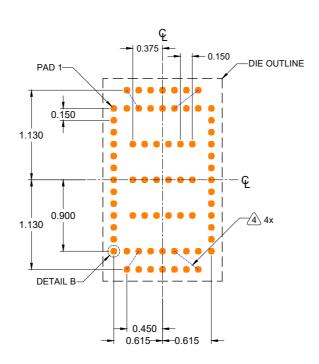
- 1. All dimensions are in millimeters (mm) and angles are in degrees
- 2. Tolerances of ±0.007mm apply to untoleranced dimensions
- 3. Dimensions in parenthesis () are for reference only





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RECOMMENDED LAND PATTERN (Substrate Top View, NSMD Design)





NOTES:

- 1. All dimensions are in millimeters (mm) and angles are in degrees.
- 2. Land Pattern exhibits substrate pads for die bump connections.
- 3. A complete layout requires additional connections and ground patterns.
- 4 Substrate circuit requires networks for redundant die bump connections. Land pattern identifies pads to connect, but layout details are not shown.

Page 2 of 2